

Product Change Notification
PCN 01/04

February 2004

Dear Sir or Madam,

We want to inform you that, in compliance with the EU directives WEEE and RHS, we plan to switch this device from a Non-Pb-free TQFP 44 package to a Pb-free TQFP44 package from August/September this year 2004. This change can be followed up by a dedicated datecode.

The plating material will be Sn.

For reflow soldering the new package fullfills the following conditions:

Average ramp-up rate (T_L to T_p)	3 °C/second max
Preheat - Temperature min (T_{Smin}) - Temperature max (T_{Smax}) - Time (min to max) (t_s)	150 °C 200 °C 60 - 120 seconds
T_{Smax} to T_L - Ramp-up rate	1.5 - 2.5 °C/second max
Time maintained above - Temperature (T_L) - Time (t_L)	217 °C 60 - 150 seconds
Peak temperature (T_p)	260 +0/-5 °C
Time within 5 °C of actual Peak	20 - 40 seconds
Ramp-down rate	6 °C/second max.
Time 25 °C to Peak temperature	8 minutes max.

This change doesn't affect the electrical behavior and quality of the product in any way.
This change doesn't affect the mechanical outline dimensions of the package.